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August 2010

### **USB1T11A** — Universal Serial Bus Transceiver

#### **Features**

- Complies with Universal Serial Bus Specification 1.1
- Utilizes Digital Inputs and Outputs to Transmit and Receive USB Cable Data
- Supports 12Mbit/s "Full Speed" and 1.5Mbit/s "Low Speed" Serial Data Transmission
- Compatible with the VHDL "Serial Interface Engine" from USB Implementers' Forum
- Supports Single-ended Data Interface
- Single 3.3V Supply
- ESD Performance: Human Body Model >9.5kV on D-, D+ pins only >4kV on all other pins

#### **Description**

The USB1T11A is a one-chip, generic USB transceiver. It is designed to allow 5.0V or 3.3V programmable and standard logic to interface with the physical layer of the Universal Serial Bus. It is capable of transmitting and receiving serial data at both full-speed (12Mbit/s) and low-speed (1.5Mbit/s) data rates.

The input and output signals of the USB1T11A conform with the "Serial Interface Engine." Implementation of the serial interface engine allows designers to make USB-compatible devices with off-the-shelf logic to modify and update the application.

### **Ordering Information**

Part Number	Operating Temperature Range	Package	Packing Method
USB1T11AM		14-Lead, Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150-Inch Narrow	Tube
USB1T11AMX	-40 to +85°C	14-Lead, Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150-Inch Narrow	Tape and Reel
USB1T11AMTC	-40 to +65 C	14-Lead, Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide	Tube
USB1T11AMTCX		14-Lead, Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide	Tape and Reel

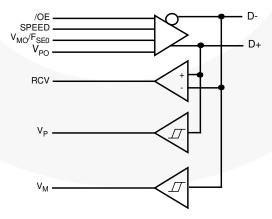


Figure 1. Logic Diagram

# **Pin Configuration**

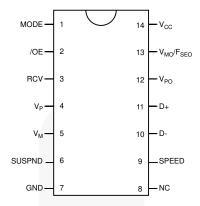


Figure 2. TSSOP and SOIC Pin Assignments

## **Pin Descriptions**

Pin Names	I/O	Description					
RCV	0	Receive Data. CMOS level output for USB differential input.					
/OE	1	Output Enable. Active When not active, the tr			nsmit data on the bus.		
Mode	ı		<b>Mode</b> . When left unconnected, a weak pull-up transistor pulls it to $V_{CC}$ and, in this GND, the $V_{MO}/F_{SEO}$ pin takes the function of $F_{SEO}$ (force SEO).				
		Inputs to differential dr	iver. (Outputs from	SIE.)			
		Mode	$V_{PO}$	V <sub>MO</sub> /F <sub>SEO</sub>	RESULT		
		0	0	0	Logic "0"		
		0	0	1	/SEO		
$V_{PO}, V_{MO}/F_{SEO}$		0	1	0	Logic "1"		
VPO, VMO/I SEO		0	1	1	/SEO		
		1	1 0 0		/SEO		
		1	0	1	Logic "0"		
		1	1	0	Logic "1"		
		1	1	1	Illegal Code		
		Buffered version of D- single ended zero (/SE	and D+. Outputs a O), error condition	re logic "0" and log is, and interconnec	ic "1." Used to detect ted speed. (Input to SIE).		
	0	$V_P$		V <sub>M</sub>	RESULT		
$V_P,V_M$		0		0	/SEO		
		0		1	Low Speed		
		1		0	Full Speed		
		0		1	Error		
D+, D-	AI/O	Data+, Data Different	ial data bus confor	rming to the Univers	sal Serial Bus standard.		
SUSPND	I	<b>Suspend</b> . Enables a low-power state while the USB bus is inactive. While the suspend pin is active, it drives the RCV pin to a logic "0" state. Both D+ and D- are 3-STATE.					
Speed	I	Edge Rate Control. Logic "1" operates at edge rates for "full speed." Logic "0" operates edge rates for "low speed."					
V <sub>CC</sub>		3.0 to 3.6 power supply	/				
GND		Ground reference.					

### **Functional Truth Table**

	Input			I/	0		Outp	uts		
Mode	V <sub>PO</sub>	V <sub>MO</sub> /F <sub>SEO</sub>	/OE	SUSPND	D+	D-	RCV	V <sub>P</sub>	V <sub>M</sub>	Result
0	0	0	0	0	0	1	0	0	1	Logic "0"
0	0	1	0	0	0	0	Undefined State	0	0	/SEO
0	1	0	0	0	1	0	1	1	0	Logic "1"
0	1	1	0	0	0	0	Undefined State	0	0	/SEO
1	0	0	0	0	0	0	Undefined State	0	0	/SEO
1	0	1	0	0	0	1	0	0	1	Logic "0"
1	1	0	0	0	1	0	1	1	0	Logic "1"
1	1	1	0	0	1	1	Undefined State	Undefined State	Undefined State	Illegal Code
Don't Care	Don't Care	Don't Care	1	0	3-State	3-State	Undefined State	Undefined State	Undefined State	D+/D- Hi-Z
Don't Care	Don't Care	Don't Care	1	1	3-State	3-State	Undefined State	Undefined State	Undefined State	D+/D- Hi-Z

### **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parame	Parameter			Max.	Unit
V <sub>CC</sub>	DC Supply Voltage			0.5	7.0	V
I <sub>IK</sub>	DC Input Diode Current, V <sub>IN</sub> <0V				-50	mA
V <sub>IN</sub>	Input Voltage <sup>(1)</sup>			0.5	5.5	V
V <sub>I/O</sub>	Input Voltage			0.5	V <sub>CC</sub> + 0.5	V
lok	Output Diode Current, Vo>Vcc or Vo<0				±50	mA
Vo	Output Voltage			0.5	V <sub>CC</sub> + 0.5	V
1	Output Source or Sink Current		V <sub>P</sub> , V <sub>M</sub> , RCV Pins		±15	mA
10	$V_0 = 0$ to $V_{CC}$		D+/D- Pins		±50	IIIA
I <sub>CC</sub> / I <sub>GND</sub>	V <sub>CC</sub> / GND Current				±100	mA
T <sub>STG</sub>	Storage Temperature Range			-60	+150	°C

#### Note:

The input and output negative voltage ratings may be exceeded if the input and output diode current ratings are
observed.

### **Recommended Operating Conditions**

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Min.	Max.	Unit
Vcc	Power Supply Operating	3.0	3.6	V
V <sub>IN</sub>	Input Voltage	0	5.5	V
V <sub>AI/O</sub>	Input Range for AI/0	0	$V_{CC}$	V
Vo	Output Voltage	0	$V_{CC}$	V
T <sub>A</sub>	Operating Ambient Temperature, Free Air	-40	+85	°C

### **DC Electrical Characteristics Digital Pins**

Over recommended range of supply voltage and operating free air temperature unless otherwise noted.  $V_{\text{CC}} = 3.0 \text{V}$  to 3.6 V.

Or make al	Devemeter	0	T <sub>A</sub> =-40 to +85°C			
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
Input Leve	ls					
V <sub>IL</sub>	Low-Level Input Voltage				0.8	V
V <sub>IH</sub>	High-Level Input Voltage		2			V
Output Lev	rels					
V	V <sub>OL</sub> Low-Level Output Voltage	I <sub>OL</sub> =4mA			0.4	V
VOL		I <sub>OL</sub> =20μA			0.1	]
V	Link Lovel Output Valtage	I <sub>OH</sub> =4mA	2.5			V
V <sub>OH</sub>	High-Level Output Voltage	I <sub>OH</sub> =20μA	V <sub>CC</sub> -0.1			]
Leakage C	urrent					
I <sub>IN</sub>	Input Leakage Current	V <sub>CC</sub> =3.0 to 3.6			±5	μΑ
I <sub>CCFS</sub>	Supply Current, Full Speed	V <sub>CC</sub> =3.0 to 3.6			5	mA
I <sub>CCLS</sub>	Supply Current, Low Speed	V <sub>CC</sub> =3.0 to 3.6			5	mA
Iccq	Quiescent Supply Current	V <sub>CC</sub> =3.0 to 3.6, V <sub>IN</sub> =V <sub>CC</sub> or GND			5	mA
I <sub>ccs</sub>	Supply Current in Suspend	V <sub>CC</sub> =3.0 to 3.6, Mode=V <sub>CC</sub>	1		10	μΑ

### DC Electrical Characteristics D+/D- Pins

Over recommended range of supply voltage and operating free air temperature unless otherwise noted.  $V_{\text{CC}} = 3.0 \text{V}$  to 3.6 V.

O. and b. a.l.	Dougnoston	O a m ditti a m a	T <sub>A</sub> =				
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units	
Input Leve	ls						
$V_{DI}$	Differential Input Sensitivity	(D+) - (D-)	0.2			V	
$V_{CM}$	Differential Common-Mode Range	Includes V <sub>DI</sub> Range	0.8	į.	2.5	V	
V <sub>SE</sub>	Single-Ended Receiver Threshold		0.8		2.0	V	
Output Lev	rels						
V <sub>OL</sub>	Static Output Low-Voltage				0.3	V	
V <sub>OH</sub>	Static Output High-Voltage	$R_L$ of $1.5k\Omega$ to $3.6V$	2.8		3.6	V	
V <sub>CR</sub>	Differential Crossover	$R_L$ of 1.5k $\Omega$ to GND	1.3		2.0	V	
Leakage C	urrent			7			
l <sub>OZ</sub>	High Z-State Data Line Leakage Current	0V <v<sub>IN&lt;3.3V</v<sub>			±5	μΑ	
Capacitano	e						
C <sub>IN</sub> <sup>(2)</sup>	Transceiver Capacitance	Pin to GND			10	pF	
C <sub>IN</sub> (-)	Capacitance Match				10	%	
Output Res	sistance			•	•		
<b>¬</b> (3)	Driver Output Resistance	Steady-State Drive	4		20	Ω	
$Z_{DRV}^{(3)}$	Resistance Match				10	%	

#### Notes:

- 2. This specification is guaranteed by design and statistical process distribution.
- 3. Excludes external resistor. To comply with USB specification 1.1, external series resistors of 24W ±1% each on D+ and D- are recommended.

### AC Electrical Characteristics D+/D- Pins, Full Speed

Over recommended range of supply voltage and operating free air temperature unless otherwise noted.  $V_{CC}=3.0V$  to 3.6V,  $C_L=50$ Pf;  $R_L=k\Omega$  on D+ to  $V_{CC}$ .

Or make al	Doromotor	O a m diti a m a	T <sub>A</sub> =			
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
Driver Cha	racteristics					
t <sub>R</sub> , t <sub>F</sub>	Rise and Fall Time	10 and 90%, Figure 4	4		20	ns
t <sub>RFM</sub>	Rise/Fall Time Matching	t <sub>R</sub> / t <sub>F</sub>	90		110	%
V <sub>CRS</sub>	Output Signal Crossover Voltage		1.3		2.0	V
<b>Driver Timi</b>	ings					
t <sub>PLH</sub>	Driver Propagation Delay (V <sub>PO</sub> ,V <sub>MO</sub> /F <sub>SEO</sub> to D+/D-)	Figure 4			18	ns
t <sub>PHZ</sub> , t <sub>PLZ</sub>	Driver Disable Delay (/OE to D+/D-)	Figure 6			13	ns
t <sub>PZH</sub> , t <sub>PZL</sub>	Driver Enable Delay (/OE to D+/D-)	Figure 6			17	ns
Receiver T	imings					
t <sub>PLH</sub>	Receiver Propagation Delay	Figure 5			16	ns
t <sub>PHL</sub>	D+/D- to RVC	Figure 5			19	ns
t <sub>PLH</sub> , t <sub>PHL</sub>	Single-ended Receiver Delay (D+/D- to V <sub>P</sub> , V <sub>M</sub> )	Figure 5			8	ns

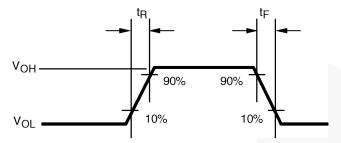
### AC Electrical Characteristics D+/D- Pins, Low Speed

Over recommended range of supply voltage and operating free air temperature unless otherwise noted.  $V_{CC}=3.0V$  to 3.6V,  $C_L=200pF$  to 600pF;  $R_L=1.5k\Omega$  on D- to  $V_{CC}$ .

Cymphal	Davamatas	Conditions	T <sub>A</sub> =			
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
Driver Cha	racteristics					
t <sub>LR</sub> , t <sub>LF</sub>	Rise and Fall Time	10 and 90%, Figure 4	75		300	ns
t <sub>RFM</sub>	Rise/Fall Time Matching	t <sub>R</sub> / t <sub>F</sub>	80		120	%
V <sub>CRS</sub>	Output Signal Crossover Voltage		1.3		2.0	V
<b>Driver Tim</b>	ings					
t <sub>PLH</sub> , t <sub>PHL</sub>	Driver Propagation Delay (V <sub>PO</sub> ,V <sub>MO</sub> /F <sub>SEO</sub> to D+/D-)	Figure 4			300	ns
t <sub>PHZ</sub> , t <sub>PLZ</sub>	Driver Disable Delay (/OE to D+/D-)	Figure 6			13	ns
t <sub>PZH</sub> , t <sub>PZL</sub>	Driver Enable Delay (/OE to D+/D-)	Figure 6			205	ns
Receiver T	imings					D
t <sub>PLH</sub> , t <sub>PHL</sub>	Receiver Propagation Delay (D+/D- to RVC)	Figure 5			18	ns
t <sub>PLH</sub> , t <sub>PHL</sub>	Single-ended Receiver Delay (D+/D- to V <sub>P</sub> , V <sub>M</sub> )	Figure 5			28	ns

### **AC Loadings and Waveforms**

V<sub>OL</sub> and V<sub>OH</sub> are the typical output voltage drops that occur with the output load. V<sub>CC</sub> never goes below 3.0V.



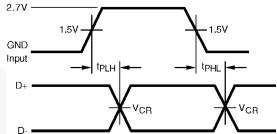
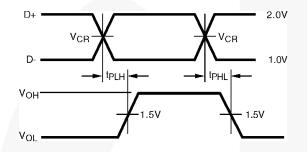


Figure 3. Rise and Fall Times

Figure 4.  $V_{PO}$ ,  $V_{MO}/F_{SEO}$  to D+/D-



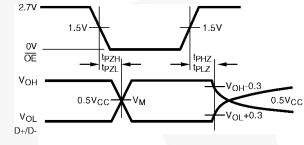
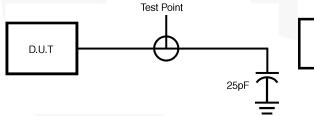


Figure 5. D+/D- to RCV, V<sub>P</sub>/V<sub>M</sub>

Figure 6. /OE to D+/D-

#### **Test Circuits and Waveforms**



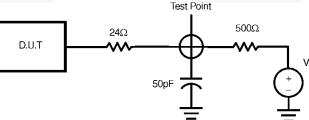
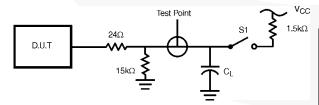


Figure 7. Load for V<sub>M</sub>/V<sub>P</sub> and RCV

Figure 8. Load for Enable and Disable Times



Test	S1
D-/LS	Close
D+/LS	Open
D-/FS	Open
D+/FS	Close

C<sub>L</sub>=50pF, Full Speed

C<sub>L</sub>=200pF, Full Speed (Minimum Timing)

C<sub>L</sub>=600pF, Full Speed (Maximum Timing)

 $1.5k\Omega$  on D-(Low Speed) or D+ (Full Speed) only.

Figure 9. Load for D+/D-

### **Physical Dimensions**

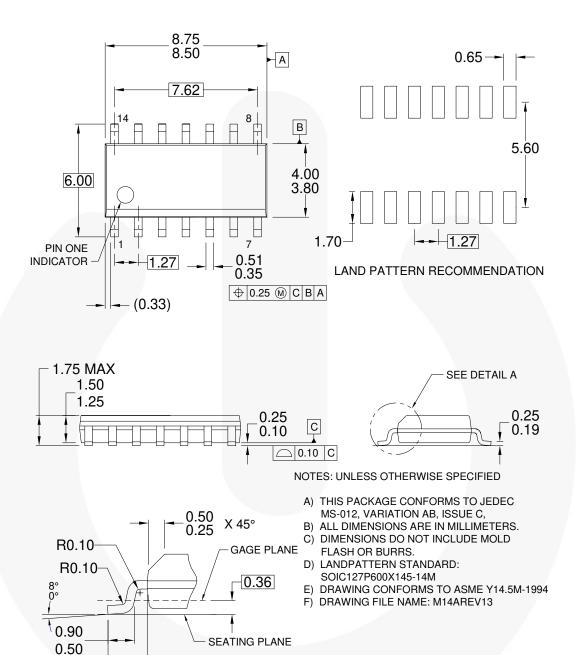


Figure 10. 14-Lead, Small Outline Integrated Circuit (SOIC) MO-012, 0.150-inch Wide

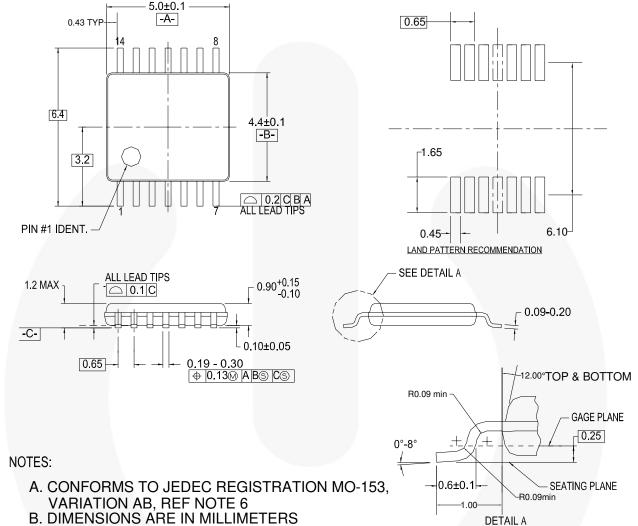
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**DETAIL A** 

(1.04)

### **Physical Dimensions**



- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
- D. DIMENSIONING AND TOLERANCES PER ANSI Y14.5M, 1982
- E. LANDPATTERN STANDARD: SOP65P640X110-14M
- F. DRAWING FILE NAME: MTC14REV6

Figure 11. 14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

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No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
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